



Material Content Data Sheet



Sales Product Name				IPD30N12S3L-31		Issued		19. January 2018	
MA#				MA001668108					
Package				PG-TO252-3-11		Weight*		370.81 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.345	0.63	0.63	6323	6323	
leadframe	non noble metal	iron	7439-89-6	0.215	0.06		581		
	inorganic material	phosphorus	7723-14-0	0.065	0.02		174		
	non noble metal	copper	7440-50-8	215.017	57.99	58.07	579853	580608	
wire	non noble metal	aluminium	7429-90-5	1.865	0.50	0.50	5030	5030	
encapsulation	organic material	carbon black	1333-86-4	1.256	0.34		3388		
	plastics	epoxy resin	-	21.983	5.93		59282		
	inorganic material	silicondioxide	60676-86-0	102.376	27.61	33.88	276085	338755	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10086	10086	
plating	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	245	246	
	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
solder	noble metal	silver	7440-22-4	0.066	0.02		179		
	non noble metal	tin	7440-31-5	0.053	0.01		143		
	non noble metal	lead	7439-92-1	2.538	0.68	0.71	6845	7167	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		52		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		16		
	non noble metal	copper	7440-50-8	19.177	5.17	5.18	51717	51785	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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